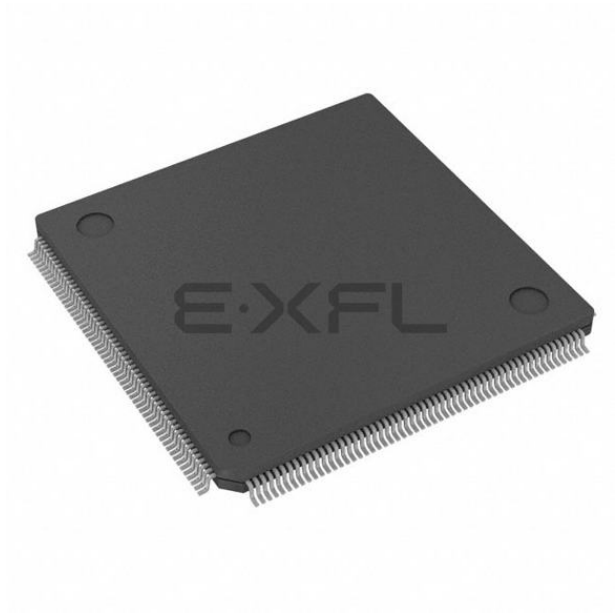
Infineon Technologies - S6E2C48L0AGL2000A Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4F
Core Size	32-Bit Single-Core
Speed	200MHz
Connectivity	CANbus, CSIO, EBI/EMI, I²C, LINbus, SD, SPI, UART/USART
Peripherals	DMA, I²S, LVD, POR, PWM, WDT
Number of I/O	190
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 32x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	216-LQFP
Supplier Device Package	216-LQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/s6e2c48l0agl2000a

4. Pin Descriptions

List of Pin Functions

The number after the underscore ("_") in pin names such as XXX_1 and XXX_2 indicates the relocated port number. For these pins, there are multiple pins that provide the same function for the same channel.

Use the extended port function register (EPFR) to select the pin.

Pin No				Pin Name	I/O circuit type	Pin state type
LQQ216	LQP176	LQS144	LBE192			
1	1	1	C1	VCC	-	-
2	2	2	B2	PA0 RTO20_0 (PPG20_0) TIOA8_0 AIN2_0 INT00_0 MADATA00_0	G	K
3	3	3	C2	PA1 RTO21_0 (PPG20_0) TIOA9_0 BIN2_0 MADATA01_0	G	I
4	4	4	C3	PA2 RTO22_0 (PPG22_0) TIOA10_0 ZIN2_0 MADATA02_0	G	I
5	5	5	D5	PA3 RTO23_0 (PPG22_0) TIOA11_0 MADATA03_0	G	I
6	6	6	D2	PA4 RTO24_0 (PPG24_0) TIOA12_0 MADATA04_0	G	I
7	7	7	D1	PA5 SIN1_0 RTO25_0 (PPG24_0) TIOA13_0 INT01_0 MADATA05_0	G	K

Pin No				Pin Name	I/O circuit type	Pin state type
LQQ216	LQP176	LQS144	LBE192			
51	41	-	L2	P5D SIN10_1 TIOB11_2 INT01_2 MADATA29_0 I2SMCLK0_0	E	K
52	42	-	L3	P5E SOT10_1 (SDA10_1) TIOA12_2 MADATA30_0 I2SDO0_0	E	I
53	43	-	M2	P5F SCK10_1 (SCL10_1) TIOB12_2 MADATA31_0 I2SWS0_0	E	I
54	44	36	M1	VSS	-	-
55	45	37	N1	VCC	-	-
56	46	38	N2	P40 SIN3_1 RTO10_0 (PPG10_0) TIOA0_0 AIN0_0 INT23_0 MCSX7_0	G	K
57	47	39	N3	P41 SOT3_1 (SDA3_1) RTO11_0 (PPG10_0) TIOA1_0 BIN0_0 MCSX6_0	G	I
58	48	40	M3	P42 SCK3_1 (SCL3_1) RTO12_0 (PPG12_0) TIOA2_0 ZIN0_0 MCSX5_0	G	I
59	49	41	L4	P43 SIN15_0 RTO13_0 (PPG12_0) TIOA3_0 INT04_0 MCSX4_0	G	K

Pin No				Pin Name	I/O circuit type	Pin state type
LQQ216	LQP176	LQS144	LBE192			
125	101	85	J11	P17 AN07 SCK11_0 (SCL11_0) TIOB2_2 ZIN1_2	F	L
126	102	-	J10	PB0 AN16 SCK6_1 (SCL6_1) TIOA9_1	F	L
127	103	-	J9	PB1 AN17 SCS60_1 TIOB9_1 INT08_1	F	M
128	104	-	H10	PB2 AN18 SCS61_1 TIOA10_1 INT09_1	F	M
129	105	-	J14	PB3 AN19 SCS62_1 TIOB10_1	F	L
130	106	86	H9	P18 AN08 SIN2_0 TIOA3_2 INT10_0	F	M
131	107	87	H12	P19 AN09 SOT2_0 (SDA2_0) TIOB3_2 INT24_1 TRACECLK	F	O
132	108	88	H14	P1A AN10 SCK2_0 (SCL2_0) TIOA4_2 TRACED0	F	N
133	109	89	G14	P1B AN11 SIN12_0 TIOB4_2 INT11_0 TRACED1	F	O
134	110	90	H13	P1C AN12 SOT12_0 (SDA12_0) TIOA5_2 TRACED2	F	N

Module	Pin name	Function	Pin No			
			LQQ 216	LQP 176	LQS 144	LBE 192
External Bus	MNALE_0	External bus interface ALE signal to control NAND Flash output pin	47	37	32	K2
	MNCLE_0	External bus interface CLE signal to control NAND Flash output pin	48	38	33	K3
	MNREX_0	External bus interface read enable signal to control NAND Flash	50	40	35	L1
	MNWEX_0	External bus interface write enable signal to control NAND Flash	49	39	34	K4
	MOEX_0	External bus interface read enable signal for SRAM	209	169	137	C5
	MWEX_0	External bus interface write enable signal for SRAM	210	170	138	B4
	MSDCLK_0	SDRAM interface SDRAM clock output pin	90	75	-	L9
	MSDCKE_0	SDRAM interface SDRAM clock enable output pin	89	74	-	M9
	MRASX_0	SDRAM interface SDRAM row active output pin	85	70	-	N8
	MCASX_0	SDRAM interface SDRAM column active output pin	86	71	-	M8
	MSDWEX_0	SDRAM interface SDRAM write enable output pin	87	72	-	N9
External Interrupt	INT00_0	External interrupt request 00 input pin	2	2	2	B2
	INT00_1		38	28	23	H3
	INT00_2		19	-	-	-
	INT01_0	External interrupt request 01 input pin	7	7	7	D1
	INT01_1		41	31	26	H6
	INT01_2		51	41	-	L2
	INT02_0	External interrupt request 02 input pin	14	13	10	E5
	INT02_1		42	32	27	J5
	INT02_2		26	-	-	-
	INT03_0	External interrupt request 03 input pin	17	16	13	F3
	INT03_1		43	33	28	J4
	INT03_2		34	24	-	G6
	INT04_0	External interrupt request 04 input pin	59	49	41	L4
	INT04_1		100	83	67	M11
	INT04_2		65	-	-	-
	INT05_0	External interrupt request 05 input pin	70	55	47	L5
	INT05_1		86	71	-	M8
	INT05_2		68	-	-	-

Module	Pin name	Function	Pin No			
			LQQ 216	LQP 176	LQS 144	LBE 192
External Interrupt	INT06_0	External interrupt request 06 input pin	80	65	55	L6
	INT06_1		87	72	-	N9
	INT06_2		103	-	-	-
	INT07_0	External interrupt request 07 input pin	82	67	57	L8
	INT07_1		88	73	-	P9
	INT07_2		102	-	-	-
	INT08_0	External interrupt request 08 input pin	114	94	78	L11
	INT08_1		127	103	-	J9
	INT08_2		119	-	-	-
	INT09_0	External interrupt request 09 input pin	123	99	83	J13
	INT09_1		128	104	-	H10
	INT09_2		120	-	-	-
	INT10_0	External interrupt request 10 input pin	130	106	86	H9
	INT10_1		138	112	-	G13
	INT10_2		149	-	-	-
	INT11_0	External interrupt request 11 input pin	133	109	89	G14
	INT11_1		139	113	-	F14
	INT11_2		151	-	-	-
	INT12_0	External interrupt request 12 input pin	194	162	132	E7
	INT12_1		169	139	-	C11
	INT12_2		175	-	-	-
	INT13_0	External interrupt request 13 input pin	184	152	122	E8
	INT13_1		170	140	-	D11
	INT13_2		176	-	-	-
	INT14_0	External interrupt request 14 input pin	192	160	130	A6
	INT14_1		171	141	-	B10
	INT14_2		201	-	-	-
	INT15_0	External interrupt request 15 input pin	193	161	131	D7
	INT15_1		172	142	-	C10
	INT15_2		206	-	-	-
	INT16_0	External interrupt request 16 input pin	25	20	17	G2
	INT16_1		45	35	30	J2
	INT17_0	External interrupt request 17 input pin	30	21	18	G3
	INT17_1		46	36	31	K1
	INT18_0	External interrupt request 18 input pin	31	22	19	G4
	INT18_1		47	37	32	K2
	INT19_0	External interrupt request 19 input pin	36	26	21	H2
	INT19_1		48	38	33	K3
	INT20_0	External interrupt request 20 input pin	91	76	60	K9
	INT20_1		89	74	-	M9

Module	Pin name	Function	Pin No			
			LQQ 216	LQP 176	LQS 144	LBE 192
GPIO	PA0	General-purpose I/O port A	2	2	2	B2
	PA1		3	3	3	C2
	PA2		4	4	4	C3
	PA3		5	5	5	D5
	PA4		6	6	6	D2
	PA5		7	7	7	D1
	PA6		8	8	8	D3
	PA7		9	9	9	D4
	PA8		14	13	10	E5
	PA9		15	14	11	F1
	PAA		16	15	12	F2
	PAB		17	16	13	F3
	PAC		18	17	14	F4
	PAD		23	18	15	F5
	PAE		24	19	16	F6
	PAF		25	20	17	G2
	PB0	General-purpose I/O port B	126	102	-	J10
	PB1		127	103	-	J9
	PB2		128	104	-	H10
	PB3		129	105	-	J14
	PB4		138	112	-	G13
	PB5		139	113	-	F14
	PB6		140	114	-	G12
	PB7		141	115	-	G11
	PB8		119	-	-	-
	PB9		120	-	-	-
	PBA		121	-	-	-
	PBB		122	-	-	-
	PBC		148	-	-	-
	PBD		149	-	-	-
	PBE		150	-	-	-
	PBF		151	-	-	-

Module	Pin name	Function	Pin No			
			LQQ 216	LQP 176	LQS 144	LBE 192
Low-Power Consumption Mode	WKUP0	Deep standby mode return signal input pin 0	158	128	104	C13
	WKUP1	Deep standby mode return signal input pin 1	14	13	10	E5
	WKUP2	Deep standby mode return signal input pin 2	70	55	47	L5
	WKUP3	Deep standby mode return signal input pin 3	212	172	140	B3
DAC	DA0	D/A converter ch.0 analog output pin	100	83	67	M11
	DA1	D/A converter ch.1 analog output pin	99	82	66	N11
VBAT	VREGCTL	On-board regulator control pin	76	61	53	N6
	VWAKEUP	The return signal input pin from a hibernation state	77	62	54	M6
SD I/F	S_CLK_0	SD memory card interface SD memory card clock output pin	38	28	23	H3
	S_CMD_0	SD memory card interface SD memory card command output	41	31	26	H6
	S_DATA1_0	SD memory card interface SD memory card data bus	36	26	21	H2
	S_DATA0_0		37	27	22	J1
	S_DATA3_0		42	32	27	J5
	S_DATA2_0		43	33	28	J4
	S_CD_0	SD memory card interface SD memory card detection pin	45	35	30	J2
	S_WP_0	SD memory card interface SD memory card write protection	44	34	29	J3
I^2S	I2SMCLK0_0	I^2S external clock pin	51	41	-	L2
	I2SDO0_0	I^2S serial transition data output pin	52	42	-	L3
	I2SWS0_0	I^2S frame synchronization signal pin	53	43	-	M2
	I2SDI0_0	I^2S serial received data input pin	34	24	-	G6
	I2SCK0_0	I^2S bit clock pin	35	25	-	H4
High-Speed Quad SPI	Q_SCK_0	SPI clock output pin	173	143	-	D10
	Q_IO0_0	SPI data input/output pin	172	142	-	C10
	Q_IO1_0		171	141	-	B10
	Q_IO2_0		170	140	-	D11
	Q_IO3_0		169	139	-	C11
	Q_CS0_0	SPI chip select output pin	174	144	-	B9
	Q_CS1_0		175	-	-	-
	Q_CS2_0		176	-	-	-

7. Handling Devices

Power-Supply Pins

In products with multiple VCC and VSS pins, respective pins at the same potential are interconnected within the device in order to prevent malfunctions such as latch-up. All of these pins should be connected externally to the power supply or ground lines, however, in order to reduce electromagnetic emission levels, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating.

Be sure to connect the current-supply source with the power pins and GND pins of this device at low impedance. It is also advisable that a ceramic capacitor of approximately 0.1 µF be connected as a bypass capacitor between VCC and VSS near this device.

A malfunction may occur when the power-supply voltage fluctuates rapidly even though the fluctuation is within the guaranteed operating range of the VCC power supply voltage. As a rule of voltage stabilization, suppress voltage fluctuation so that the fluctuation in VCC ripple (peak-to-peak value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the standard VCC value, and the transient fluctuation rate does not exceed 0.1V/µs at a momentary fluctuation such as switching the power supply.

Crystal Oscillator Circuit

Noise near the X0/X1 and X0A/X1A pins may cause the device to malfunction. Design the printed circuit board so that X0/X1, X0A/X1A pins, the crystal oscillator (or ceramic oscillator), and the bypass capacitor to ground are located as close to the device as possible.

It is strongly recommended that the PC board artwork be designed such that the X0/X1 and X0A/X1A pins are surrounded by ground plane, as this is expected to produce stable operation.

Evaluate the oscillation introduced by the use of the crystal oscillator by your mount board.

Sub Crystal Oscillator

The sub-oscillator circuit for devices in this family is low gain to keep current consumption low. To stabilize the oscillation, Cypress recommends a crystal oscillator that meets the following conditions:

■Surface mount type
Size: More than 3.2 mm × 1.5 mm
Load capacitance: approximately 6 pF to 7 pF

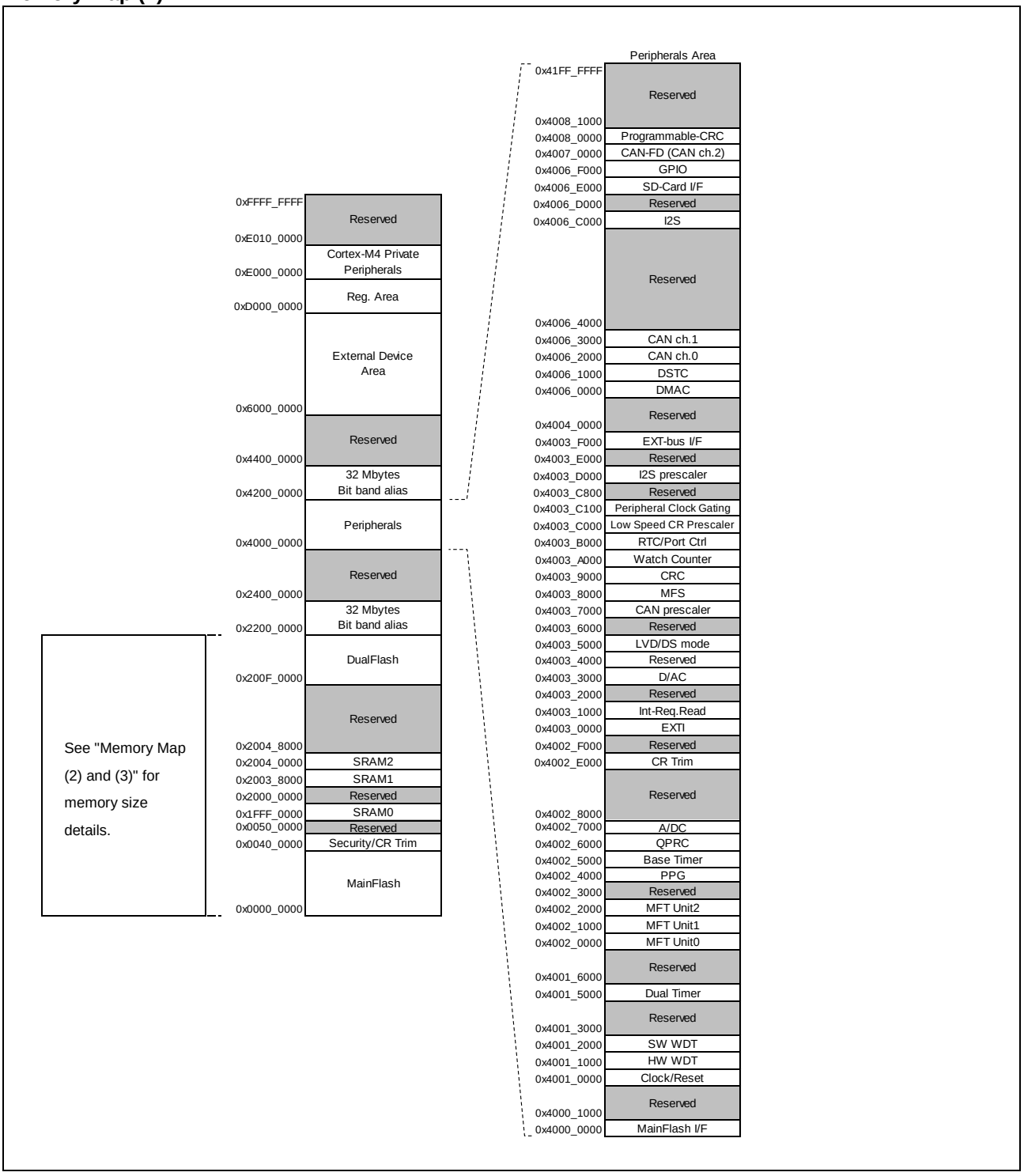
■Lead type
Load capacitance: approximately 6 pF to 7 pF

9. Memory Size

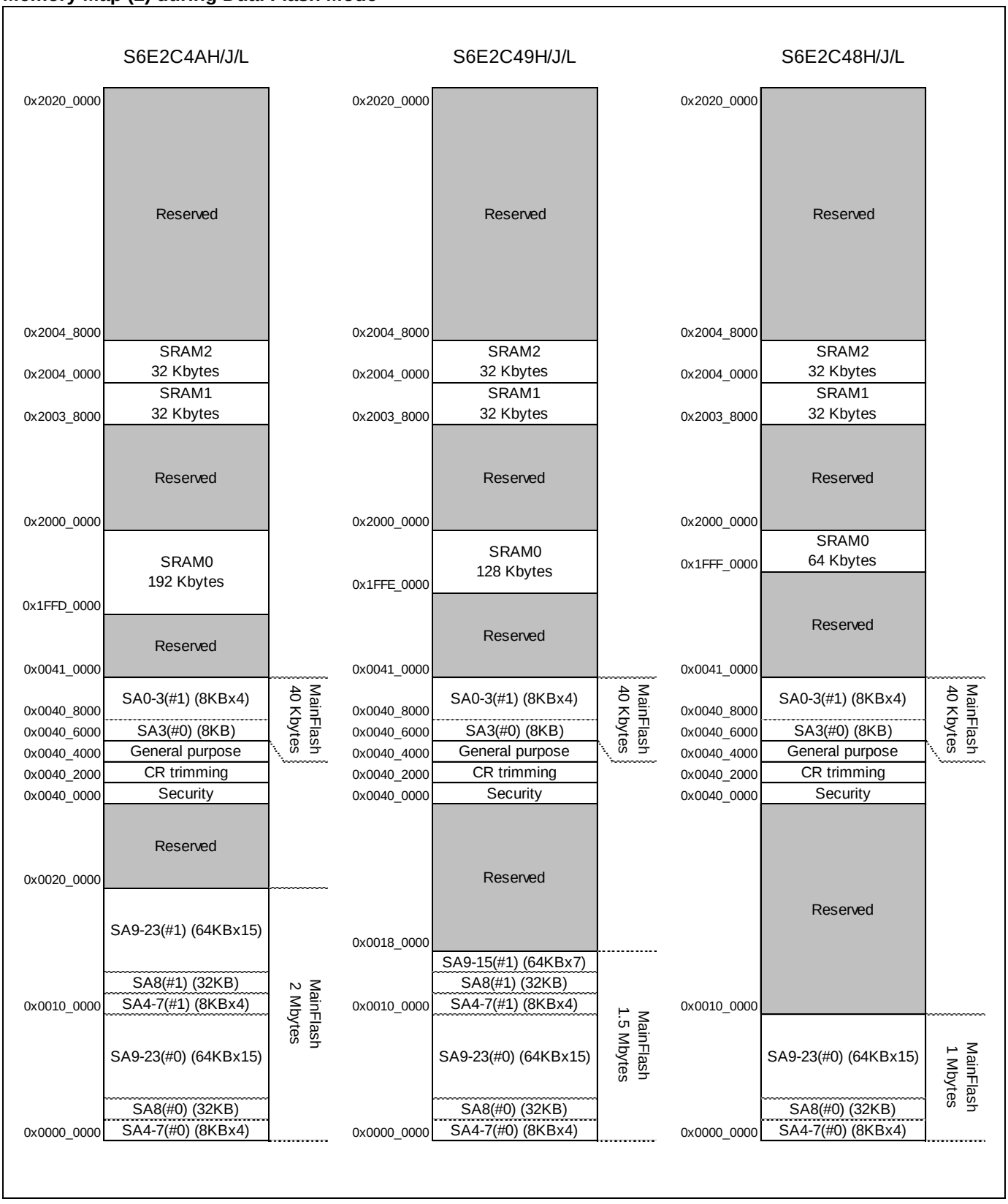
See Memory size in 1. Product Lineup to confirm the memory size.

10. Memory Map

Memory Map (1)



Memory Map (2) during Dual Flash Mode



List of VBAT Domain Pin Status

VBAT Pin Status Type	Function Group	Power-on reset*1	INITX Input State	Device Internal Reset State	Run mode or Sleep mode State	Timer mode, RTC mode, or Stop mode State		Deep Standby RTC mode or Deep Standby Stop mode State		Return From Deep Standby Mode State	VBAT RTC Mode State	Return From VBAT RTC Mode State
		Power Supply Unstable	Power Supply Stable		Power Supply Stable	Power Supply Stable		Power Supply Stable		Power Supply Stable	Power Supply Stable	Power Supply Stable
		-	INITX=0	INITX=1	INITX=1	INITX=1		INITX=1		INITX=1	-	-
		-	-	-	-	SPL=0	SPL=1	SPL=0	SPL=1	-	-	-
S	GPIO selected	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Setting prohibition	-
	Sub crystal oscillator input pin/ external sub clock input selected	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Input enabled	Maintain previous state	Maintain previous state
T	GPIO selected	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Setting prohibition	-
	External sub clock input selected	Setting disabled	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state
	Sub crystal oscillator output pin	Hi-Z/ internal input fixed at 0/ or input enable	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state/ When oscillation stops, Hi-Z*2	Maintain previous state/ When oscillation stops, Hi-Z*2	Maintain previous state/ When oscillation stops, Hi-Z*2	Maintain previous state/ When oscillation stops, Hi-Z*2	Maintain previous state	Maintain previous state	Maintain previous state
U	Resource selected	Hi-Z	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state	Maintain previous state
	GPIO selected											

*1: When VBAT and VCC power on.

*2: When the SOSCNTL bit in the WTOSCCNT register is 0, the sub crystal oscillator output pin is maintained in the previous state. When the SOSCNTL bit in the WTOSCCNT register is 1, oscillation is stopped at Stop mode and Deep Standby Stop mode

12.2 Recommended Operating Conditions

Parameter		Symbol	Conditions	Value		Unit	Remarks
				Min	Max		
Power supply voltage		V_{CC}	-	2.7 *3	5.5	V	
Power supply voltage (VBAT)		V_{BAT}	-	1.65	5.5	V	
Analog power supply voltage		AV_{CC}	-	2.7	5.5	V	$AV_{CC} = V_{CC}$
Analog reference voltage		AVRH	-	*2	AV_{CC}	V	
		AVRL	-	AV_{SS}	AV_{SS}	V	
Operating temperature	Junction temperature	T_J	-	- 40	+ 125	°C	
	Ambient temperature	T_A	-	-40	*1	°C	

*1: The maximum temperature of the ambient temperature (T_A) can guarantee a range that does not exceed the junction temperature (T_J).
The calculation formula of the ambient temperature (T_A) is:

$T_A (Max) = T_J(Max) - Pd(Max) \times \theta_{JA}$

Pd: Power dissipation (W)
θ_{JA}: Package thermal resistance (°C/W)

$Pd (Max) = V_{CC} \times I_{CC} (Max) + \Sigma (I_{OL} \times V_{OL}) + \Sigma ((V_{CC}-V_{OH}) \times (- I_{OH}))$

I_{OL}: L level output current
I_{OH}: H level output current
V_{OL}: L level output voltage
V_{OH}: H level output voltage

*2: The minimum value of analog reference voltage depends on the value of compare clock cycle (t_{CCK}). See 12.5. 12-bit A/D Converter for the details.

*3: For the voltage range between V_{cc}(min) and the low voltage detection reset (VDH), the MCU must be clocked from either the High-speed CR or the low-speed CR."

12.4.6 Operating Conditions of Main PLL (in the Case of Using Built-in High-speed CR Clock for Input Clock of Main PLL)

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
PLL oscillation stabilization wait time*1 (lock up time)	t_{LOCK}	100	-	-	µs	
PLL input clock frequency	f_{PLLI}	3.8	4	4.2	MHz	
PLL multiplication rate	-	50	-	95	multiplier	
PLL macro oscillation clock frequency	f_{PLLO}	190	-	400	MHz	
Main PLL clock frequency *2	f_{CLKPLL}	-	-	200	MHz	

*1: Time from when the PLL starts operating until the oscillation stabilizes

*2: For more information about Main PLL clock (CLKPLL), see Chapter 2-1: Clock in FM4 Family Peripheral Manual Main Part (002-04856).

Note:

- *The High-speed CR clock (CLKHC) should be set with frequency/temperature trimming to act as the source clock of the Main PLL.*

12.4.7 Reset Input Characteristics

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Typ		
Reset input time	t_{INITX}	INITX	-	500	-	ns	

12.4.8 Power-On Reset Timing

(V_{SS} = 0V)

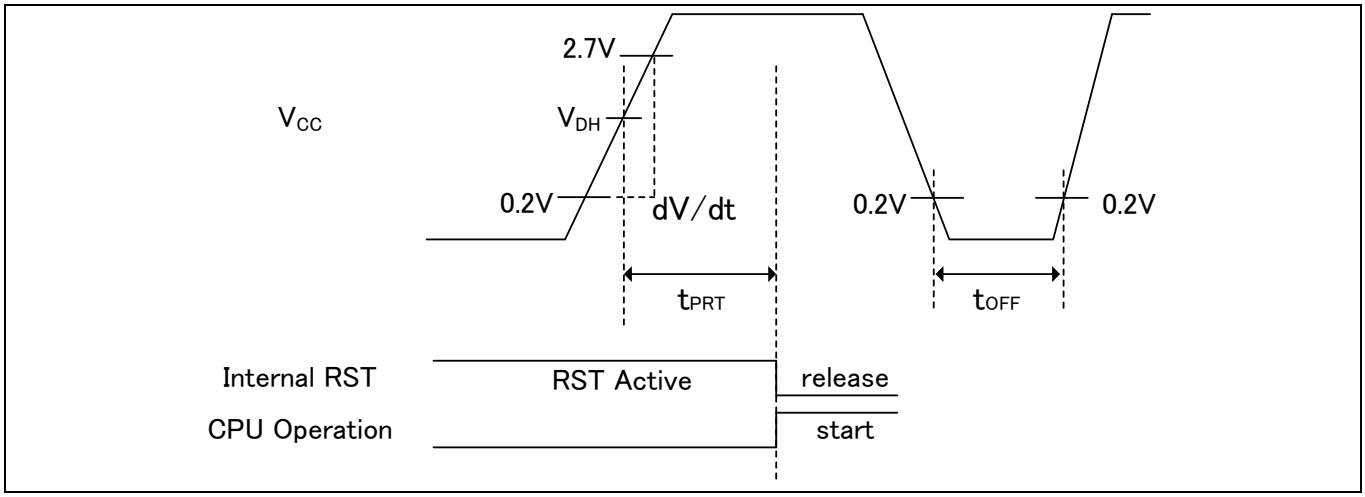
Parameter	Symbol	Pin Name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply shut down time	t_{OFF}	VCC	-	1	-	-	ms	*1
Power ramp rate	dV/dt		V_{CC}: 0.2V to 2.70V	0.6	-	1000	mV/µs	*2
Time until releasing Power-on reset	t_{PRT}		-	0.33	-	0.60	ms	

*1: V_{CC} must be held below 0.2V for a minimum period of t_{OFF}. Improper initialization may occur if this condition is not met.

*2: This dV/dt characteristic is applied at the power-on of cold start (t_{OFF}>1ms).

Note:

- *If t_{OFF} cannot be satisfied designs must assert external reset(INITX) at power-up and at any brownout event per 12. 4. 7.*



Glossary

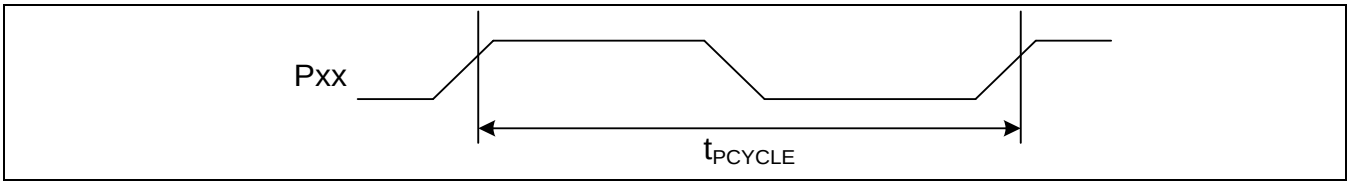
- V_{DH}: detection voltage of Low Voltage detection reset. See “12.7. Low-Voltage Detection Characteristics”.

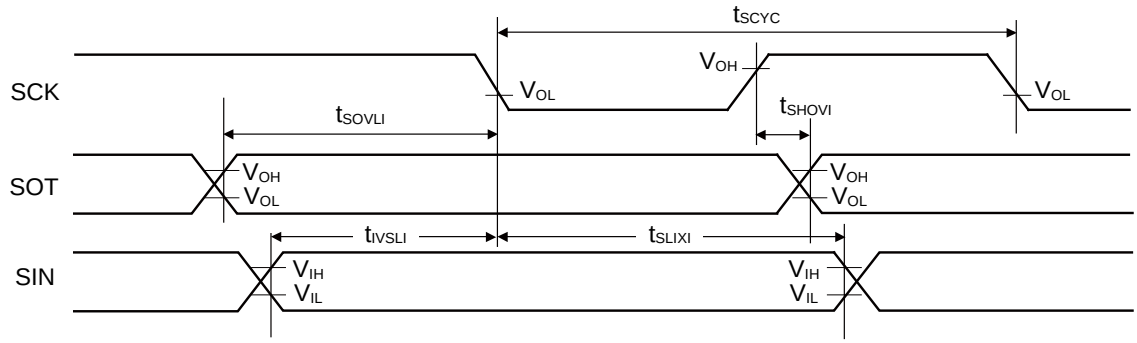
12.4.9 GPIO Output Characteristics

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

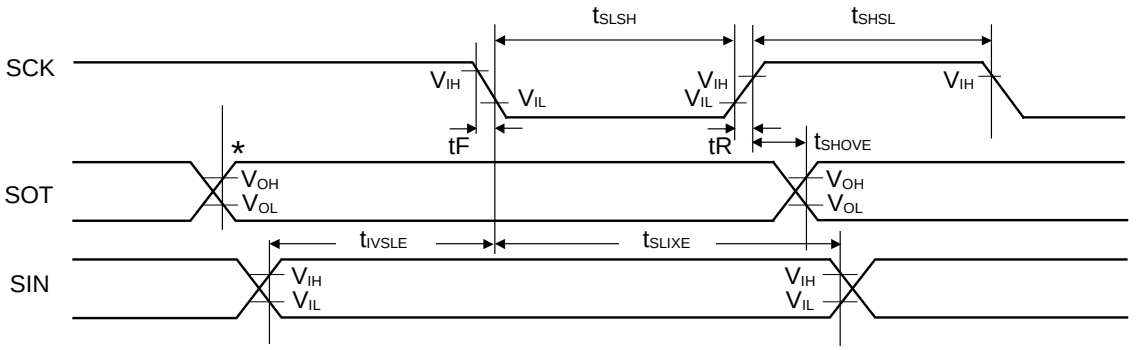
Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Typ		
Output frequency	t_{PCYCLE}	Pxx*	V_{CC} ≥ 4.5 V	-	50	MHz	
			V_{CC} < 4.5 V	-	32	MHz	

*: GPIO is a target.



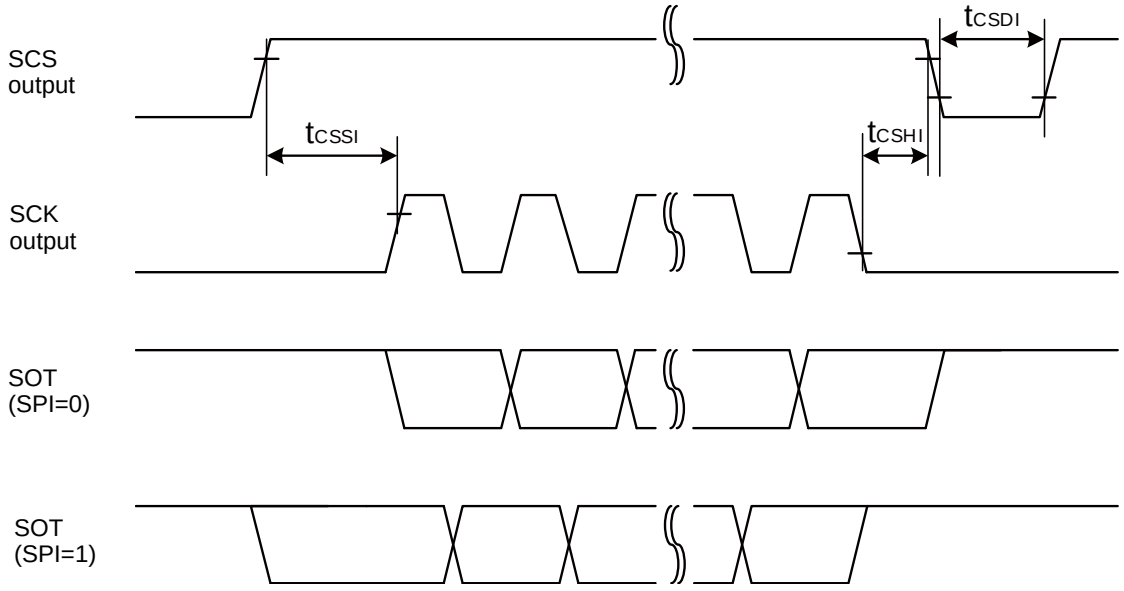


MS bit = 0

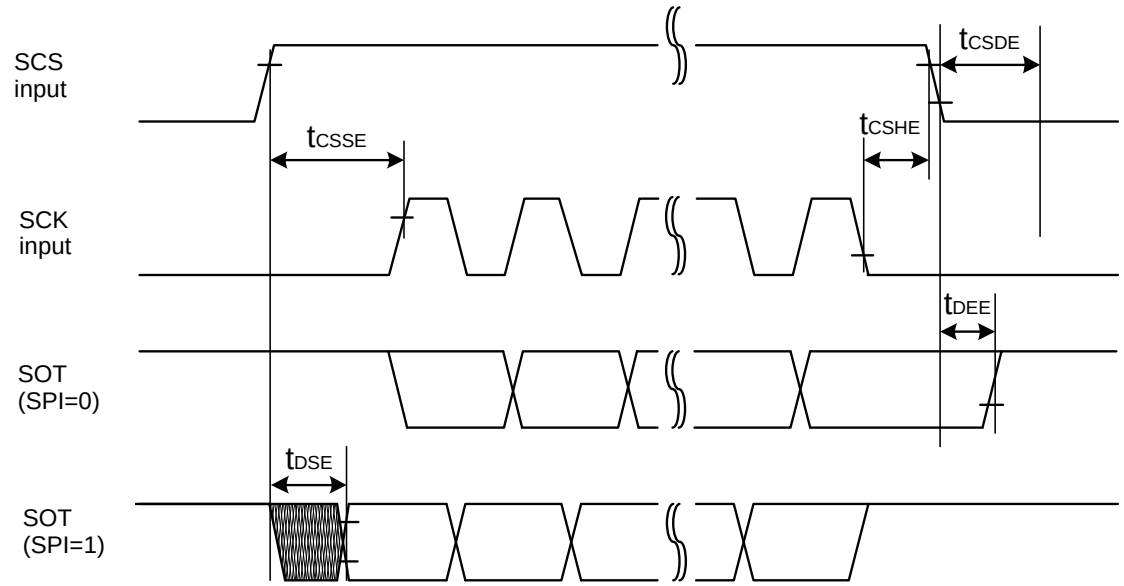


MS bit = 1

*: Changes when writing to TDR register



MS bit = 0



MS bit = 1

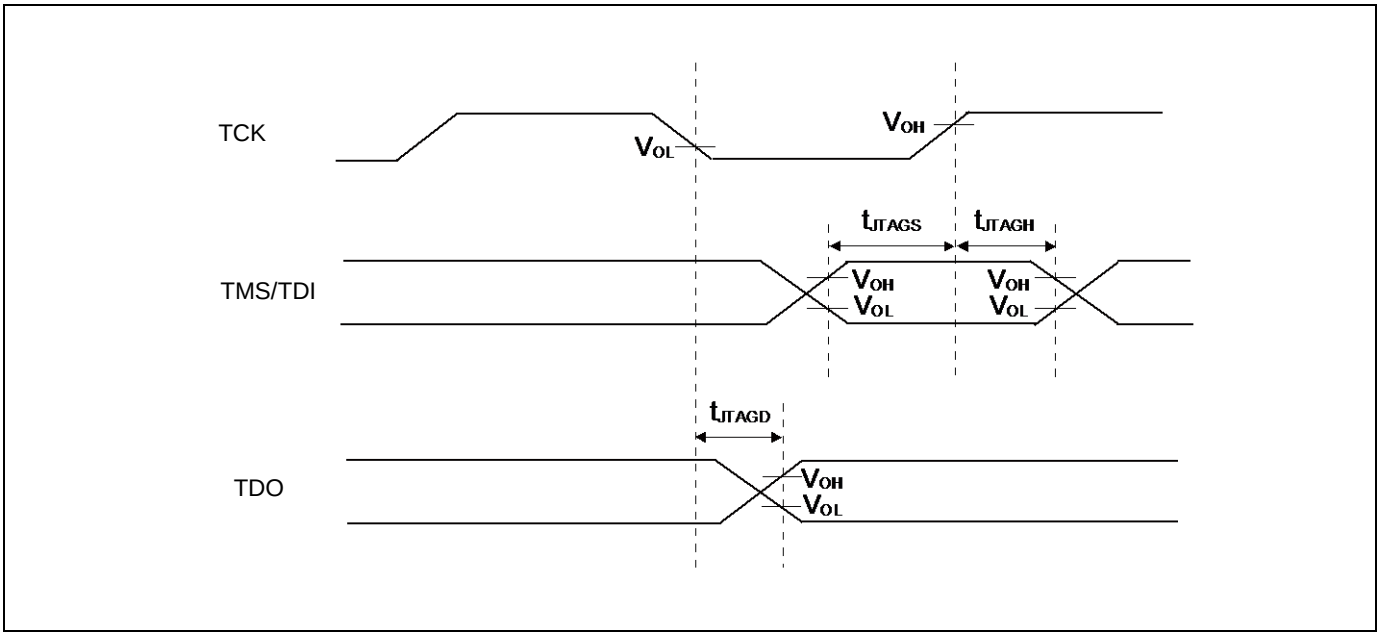
12.4.18 JTAG Timing

(V_{CC} = 2.7V to 5.5V, V_{SS} = 0V)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
TMS, TDI setup time	t_{JTAGS}	TCK, TMS, TDI	$V_{CC} \geq 4.5$ V	15	-	ns	
			$V_{CC} < 4.5$ V				
TMS, TDI hold time	t_{JTAGH}	TCK, TMS, TDI	$V_{CC} \geq 4.5$ V	15	-	ns	
			$V_{CC} < 4.5$ V				
TDO delay time	t_{JTAGD}	TCK, TDO	$V_{CC} \geq 4.5$ V	-	25	ns	
			$V_{CC} < 4.5$ V	-	45		

Note:

- *When the external load capacitance C_L = 30 pF.*



12.6 12-bit D/A Converter

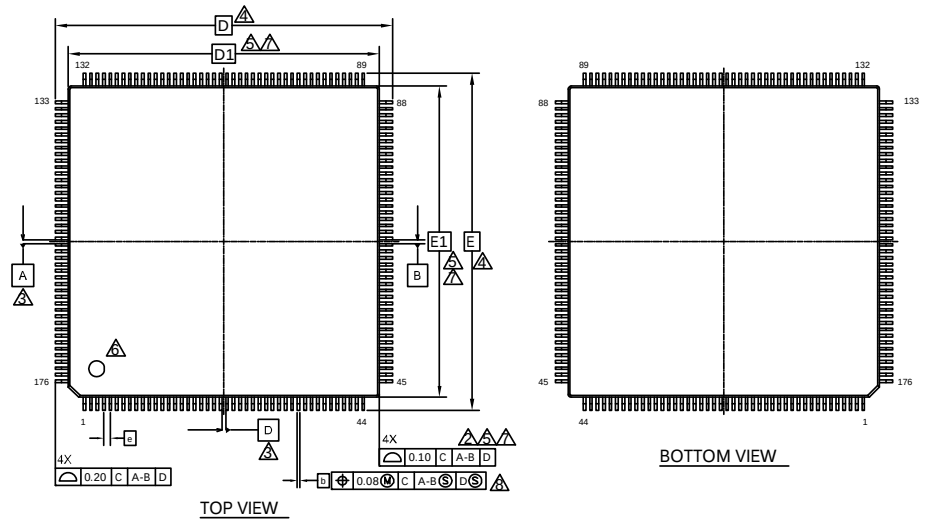
Electrical Characteristics for the D/A Converter

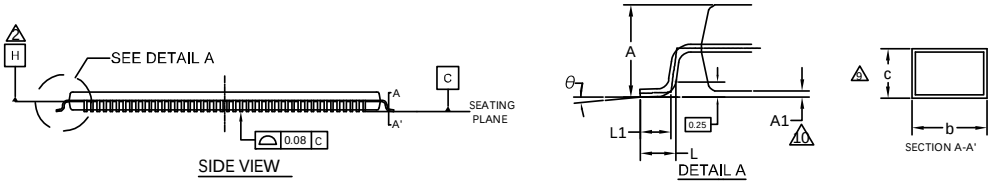
(V_{CC} = AV_{CC} = 2.7V to 5.5V, V_{SS} = AV_{SS} = 0V)

Parameter	Symbol	Pin Name	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	-	DAx	-	-	12	bit	
Conversion time	t_{C20}		0.56	0.69	0.81	µs	Load 20 pF
	t_{C100}		2.79	3.42	4.06	µs	Load 100 pF
Integral nonlinearity*	INL		- 16	-	+ 16	LSB	
Differential nonlinearity*	DNL		- 0.98	-	+ 1.5	LSB	
Output voltage offset	V_{OFF}		-	-	+ 10	mV	When setting 0x000
			- 20.0	-	+ 1.4	mV	When setting 0xFFF
Analog output impedance	R_O		3.10	3.80	4.50	kΩ	D/A operation
			2.0	-	-	MΩ	When D/A stop
Power supply current*	IDDA	AVCC	260	330	410	µs	D/A 1ch operation AV_{CC} = 3.3 V
			400	510	620	µs	D/A 1ch operation AV_{CC} = 5.0 V
	IDSA		-	-	14	µs	When D/A stop

*: During no load

Package Type	Package Code
LQFP 176	LQP 176





SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.05	—	0.15
b	0.17	0.22	0.27
c	0.09	—	0.20
D	26.00 BSC		
D1	24.00 BSC		
e	0.50 BSC		
E	26.00 BSC		
E1	24.00 BSC		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
θ	0°	—	8°

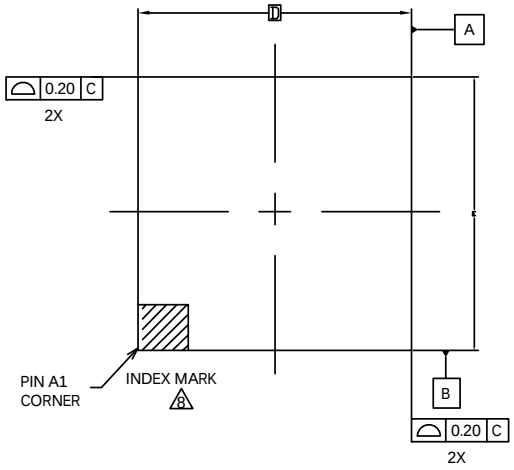
NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

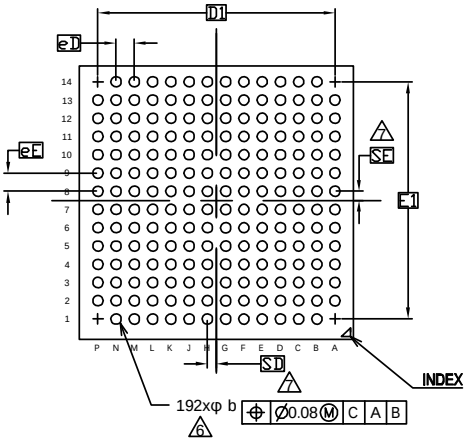
002-15150 **

PACKAGE OUTLINE, 176 LEAD LQFP
24.0X24.0X1.7 MM LQP176 REV**

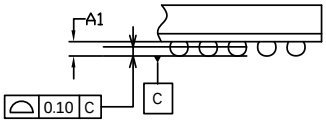
Package Type	Package Code
PFBGA 192	LBE 192



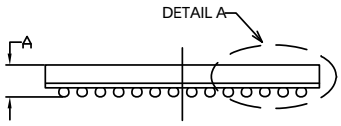
TOP VIEW



BOTTOM VIEW



DETAIL A



SIDE VIEW

SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	——	——	1.45
A1	0.25	0.35	0.45
D	12.00 BSC		
E	12.00 BSC		
D1	10.40 BSC		
E 1	10.40 BSC		
MD	14		
ME	14		
n	192		
Φb	0.35	0.45	0.55
eD	0.80 BSC		
eE	0.80 BSC		
SD / SE	0.40 BSC		

NOTES

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS AND TOLERANCES METHODS PER ASME Y14.5-2009. THIS OUTLINE CONFORMS TO JEP95, SECTION 4.5.
3. BALL POSITION DESIGNATION PER JEP95, SECTION 3, SPP-010.
4. "e" REPRESENTS THE SOLDER BALL GRID PITCH.
5. SYMBOL "MD" IS THE BALL MATRIX SIZE IN THE "D" DIRECTION. SYMBOL "ME" IS THE BALL MATRIX SIZE IN THE "E" DIRECTION. n IS THE NUMBER OF POPULATED SOLDER BALL POSITIONS FOR MATRIX SIZE MD X ME.
6. DIMENSION "b" IS MEASURED AT THE MAXIMUM BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
7. "SD" AND "SE" ARE MEASURED WITH RESPECT TO DATUMS A AND B AND DEFINE THE POSITION OF THE CENTER SOLDER BALL IN THE OUTER ROW. WHEN THERE IS AN ODD NUMBER OF SOLDER BALLS IN THE OUTER ROW, "SD" OR "SE" =0. WHEN THERE IS AN EVEN NUMBER OF SOLDER BALLS IN THE OUTER ROW, "SD" = eD/2 AND "SE" = eE/2.
8. A1 CORNER TO BE IDENTIFIED BY CHAMFER, LASER OR INK MARK. METALLIZED MARK INDENTATION OR OTHER MEANS.
9. "+" INDICATES THE THEORETICAL CENTER OF DEPOPULATED BALLS.

002-13493 **

PACKAGE OUTLINE, 192 BALL FBGA
12.00X12.00X1.45 MM LBE192 REV**